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(12) **United States Design Patent**
Buber

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(54) **SENSOR MODULE**

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(73) Assignee: **Microtronics Engineering GmbH** (AT)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **10-04**

(52) **U.S. Cl.**
USPC **D10/81**

(58) **Field of Classification Search**
USPC D10/46, 81
CPC G01N 1/2273; G01N 2001/2276; G01N 2001/2279; G01N 7/00; G01N 7/02; G01N 7/04; G01N 7/06; G01N 7/08; G01N 7/10; G01N 7/12; G01N 7/14; G01N 7/16; G01N 7/18; G01N 7/20; G01N 7/22; G01N 33/009–33/0075; H04B 17/23
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D307,559 S *	5/1990	Parker	D10/81	
6,945,127 B2 *	9/2005	Van Netten	G01N 1/2205 73/863.23	
D522,145 S *	5/2006	Best	D10/81	
7,334,453 B2 *	2/2008	Trakumas	G01N 1/2208 73/28.01	
7,597,015 B2 *	10/2009	Harley	G01N 1/2208 73/28.05	
8,689,648 B1 *	4/2014	Heff	G01N 1/2273 73/863.22	

* cited by examiner

Primary Examiner — Antoine D Davis
(74) *Attorney, Agent, or Firm* — Design IP

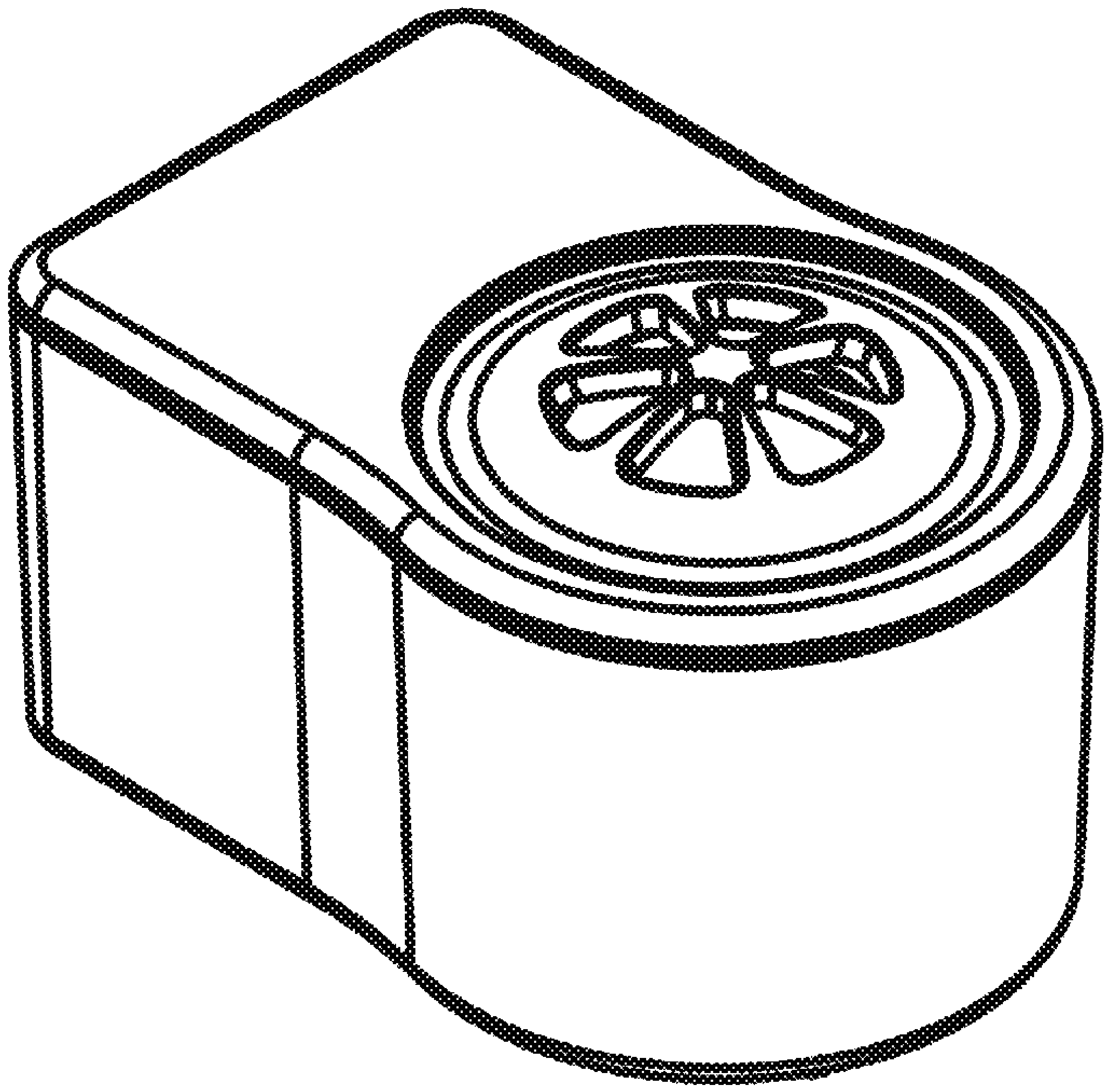
(57) **CLAIM**

The ornamental design for a sensor module, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of an embodiment of a sensor module showing my new design;
FIG. **2** is a front elevation view thereof;
FIG. **3** is a rear elevation view thereof;
FIG. **4** is a left side elevation view thereof;
FIG. **5** is a right side elevation view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom perspective view thereof.

1 Claim, 7 Drawing Sheets



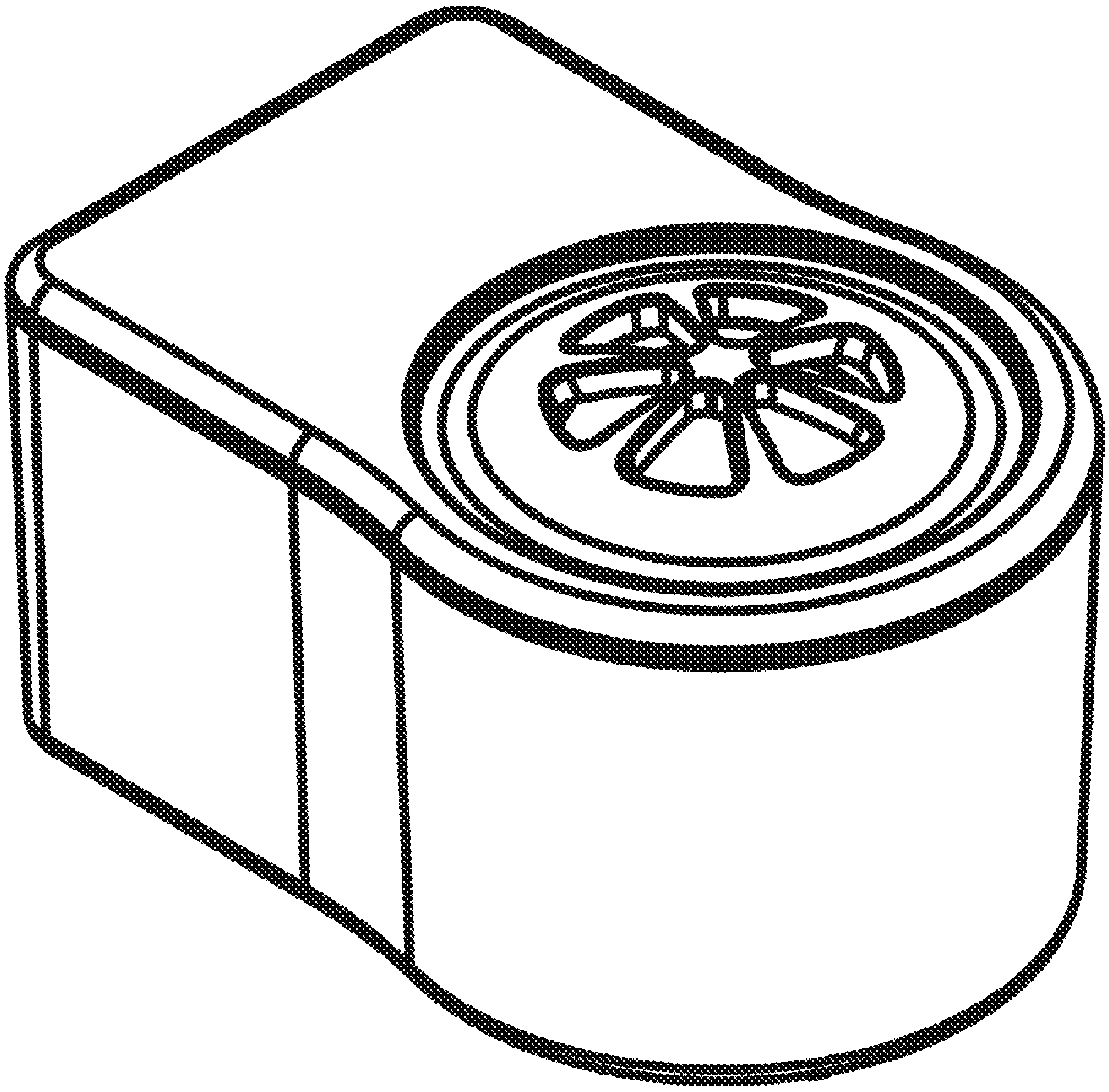


FIG. 1

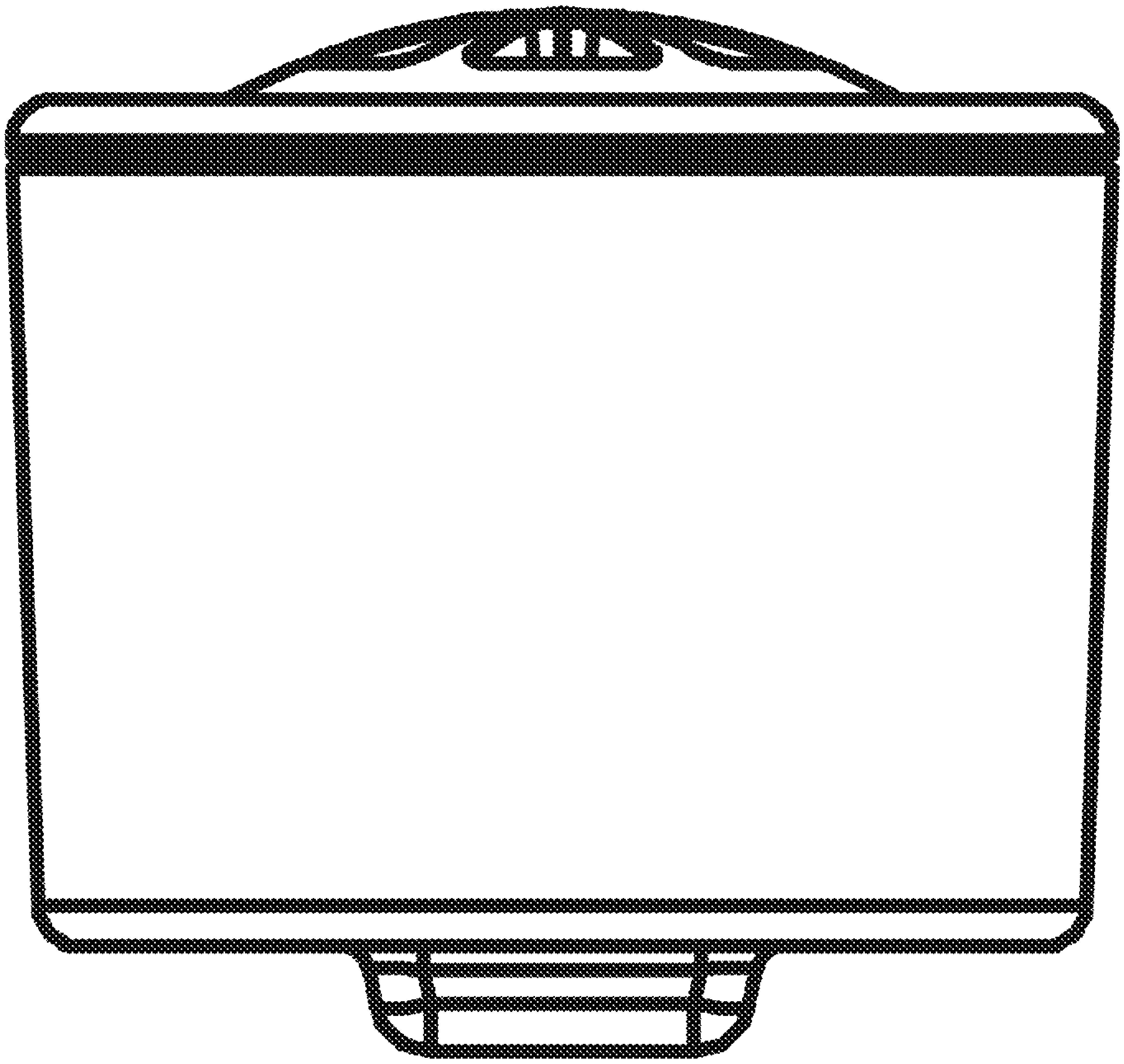


FIG. 2

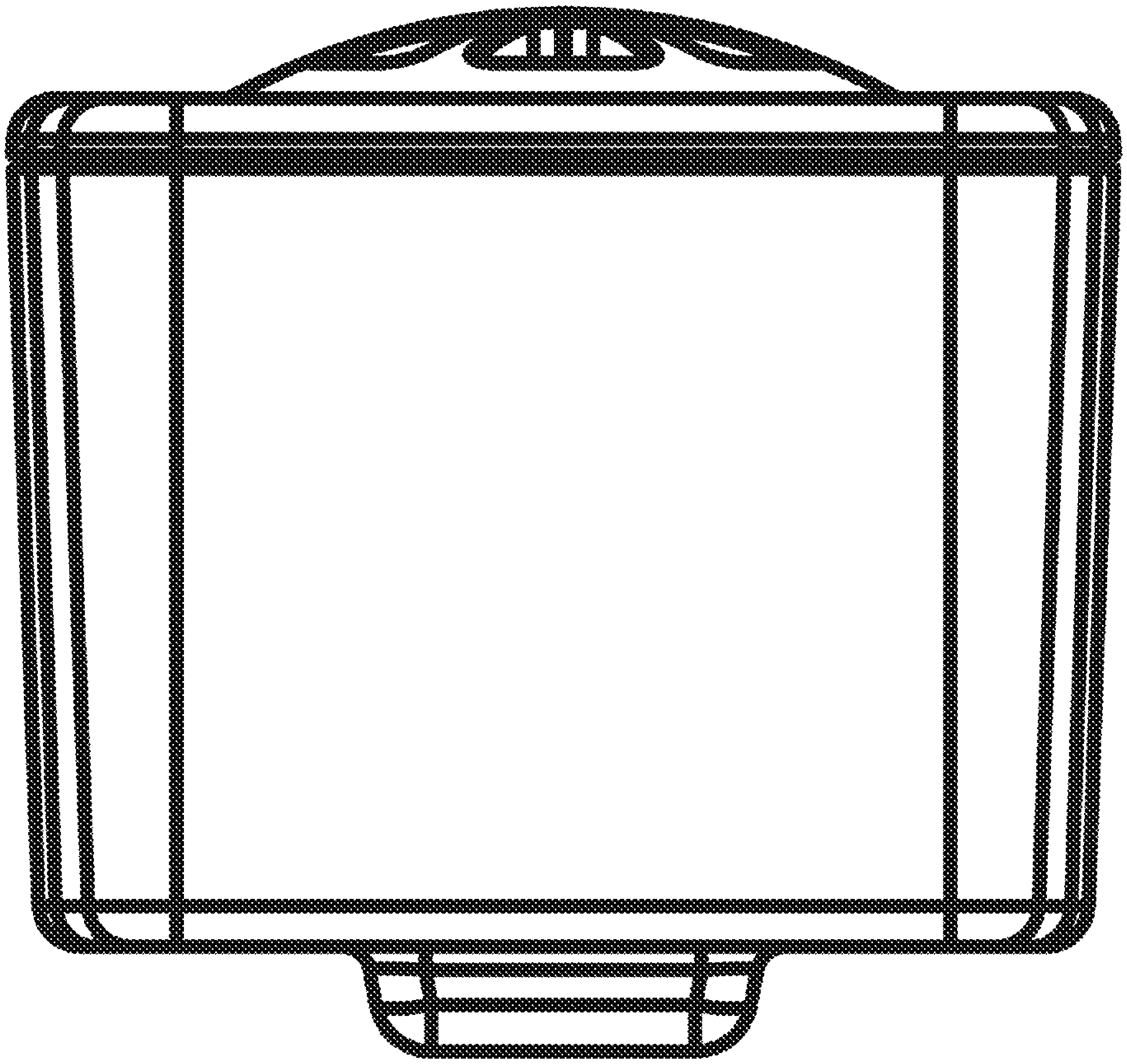


FIG. 3

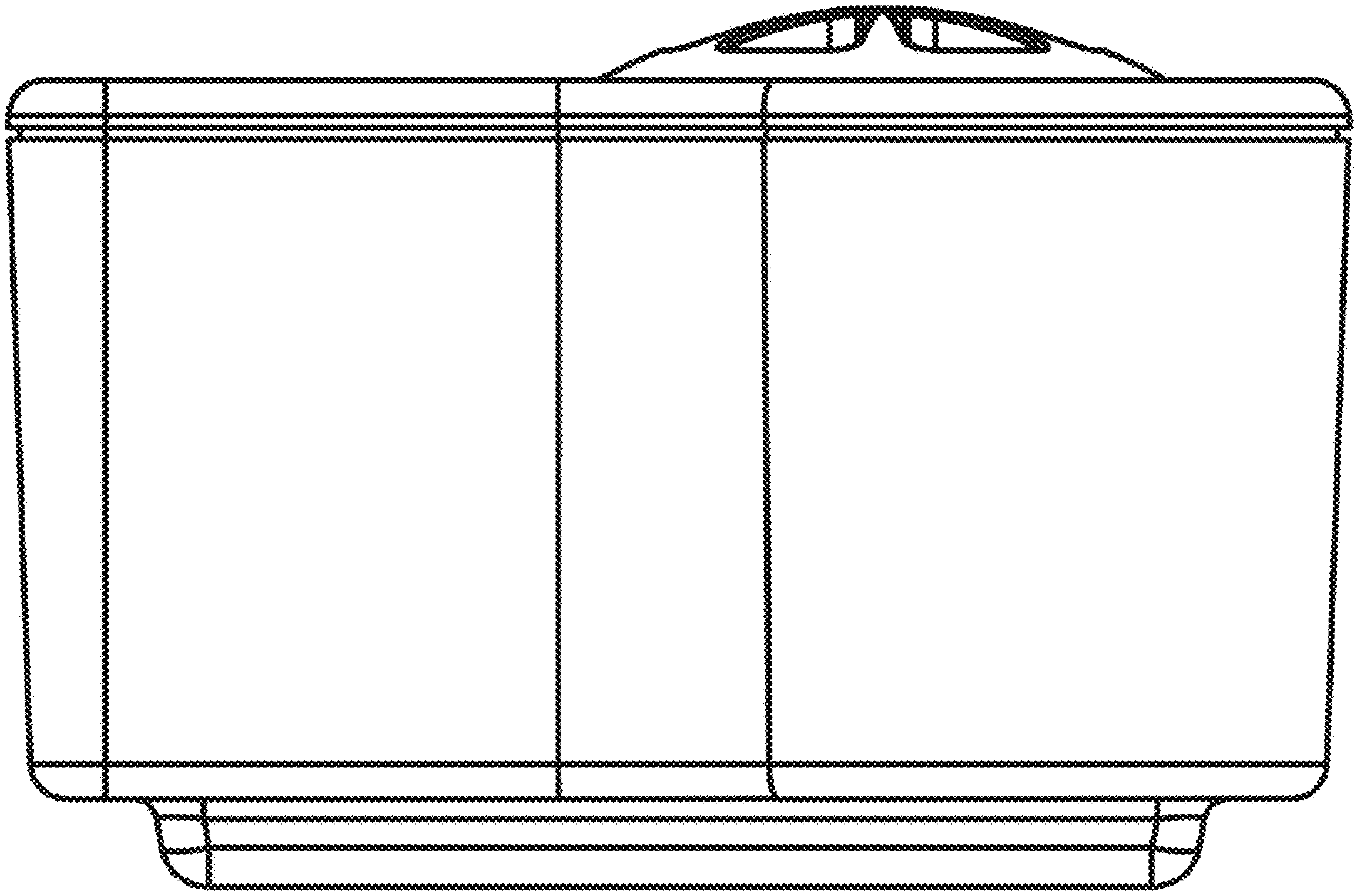


FIG. 4

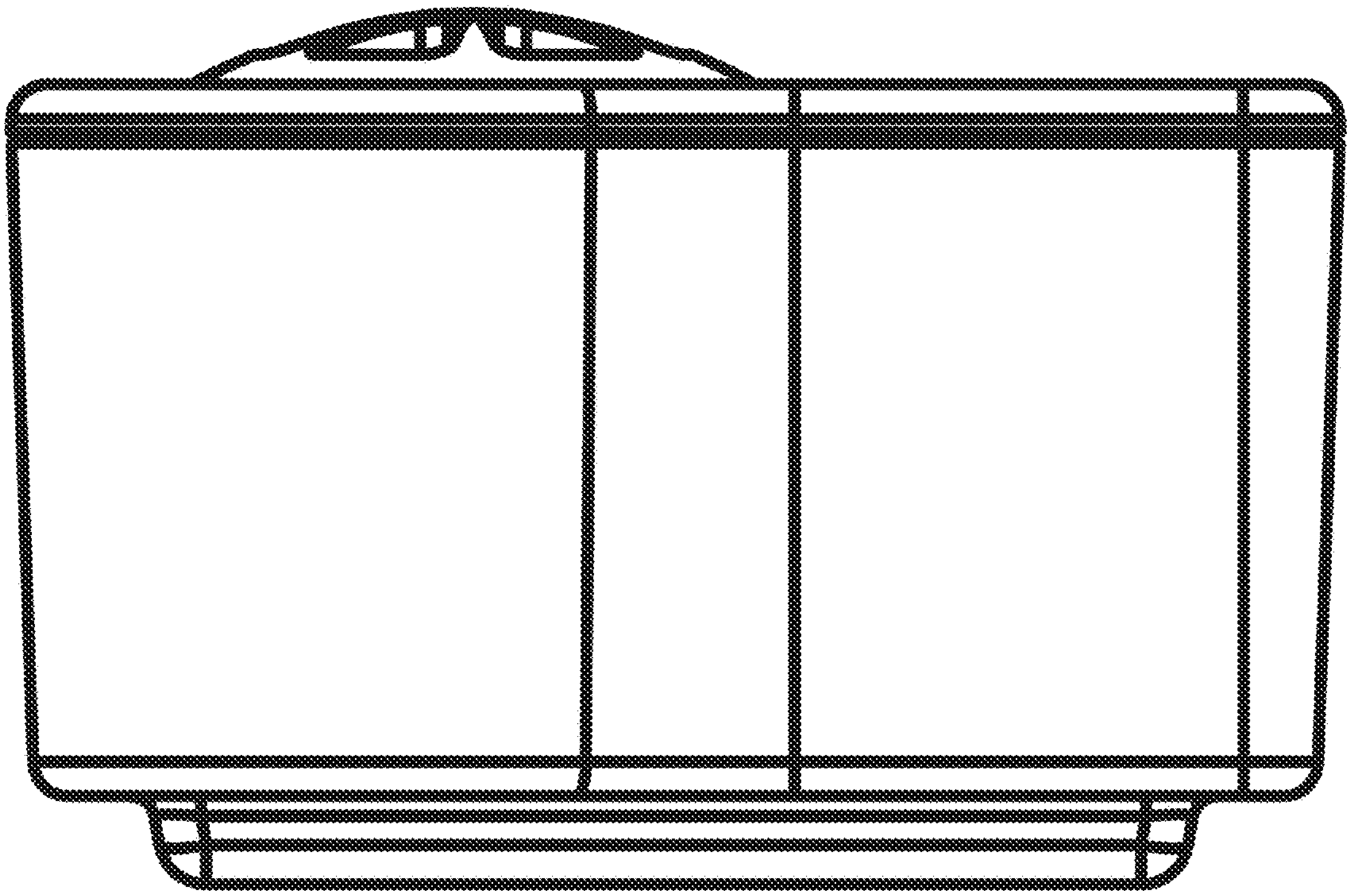


FIG. 5

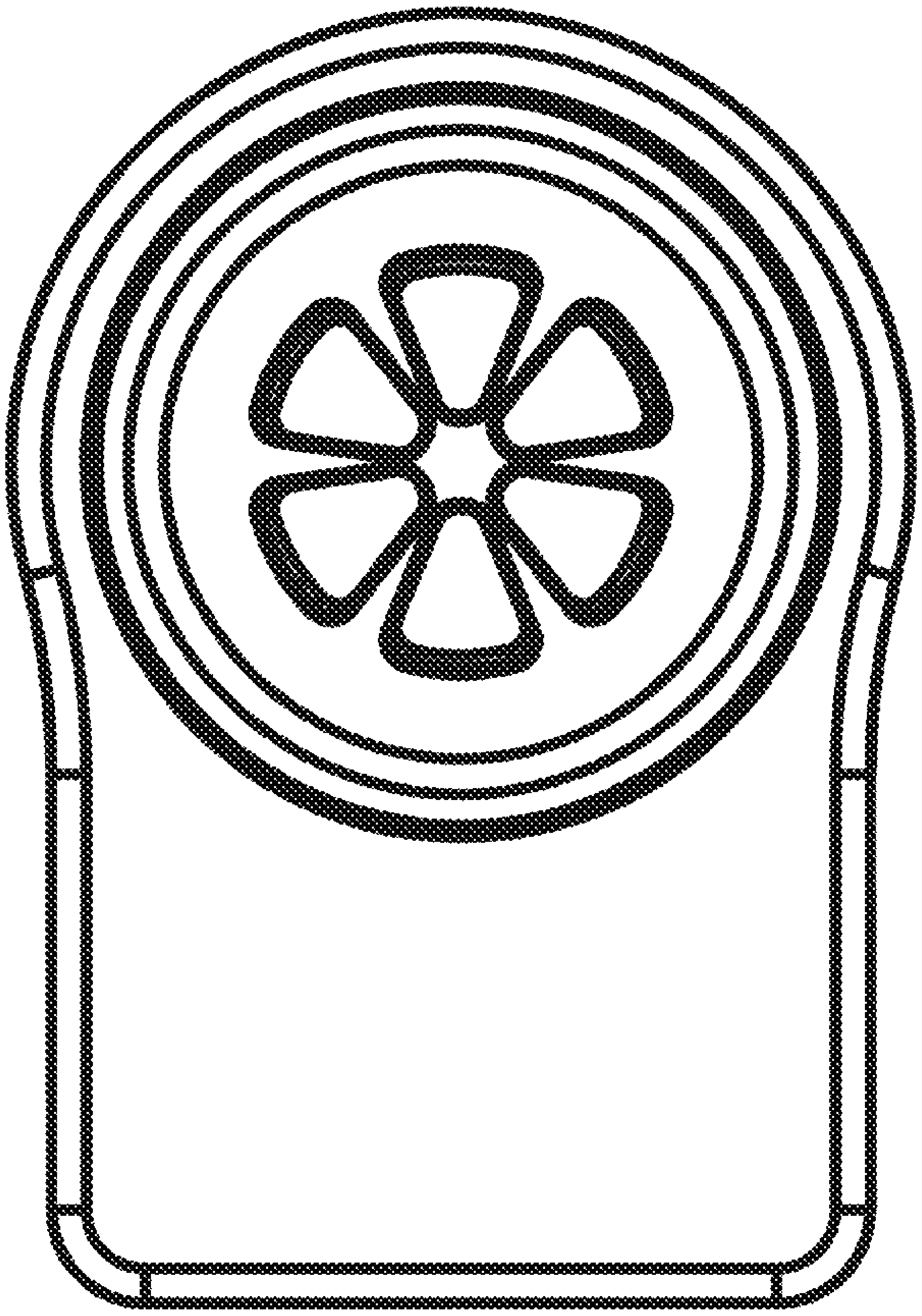


FIG. 6

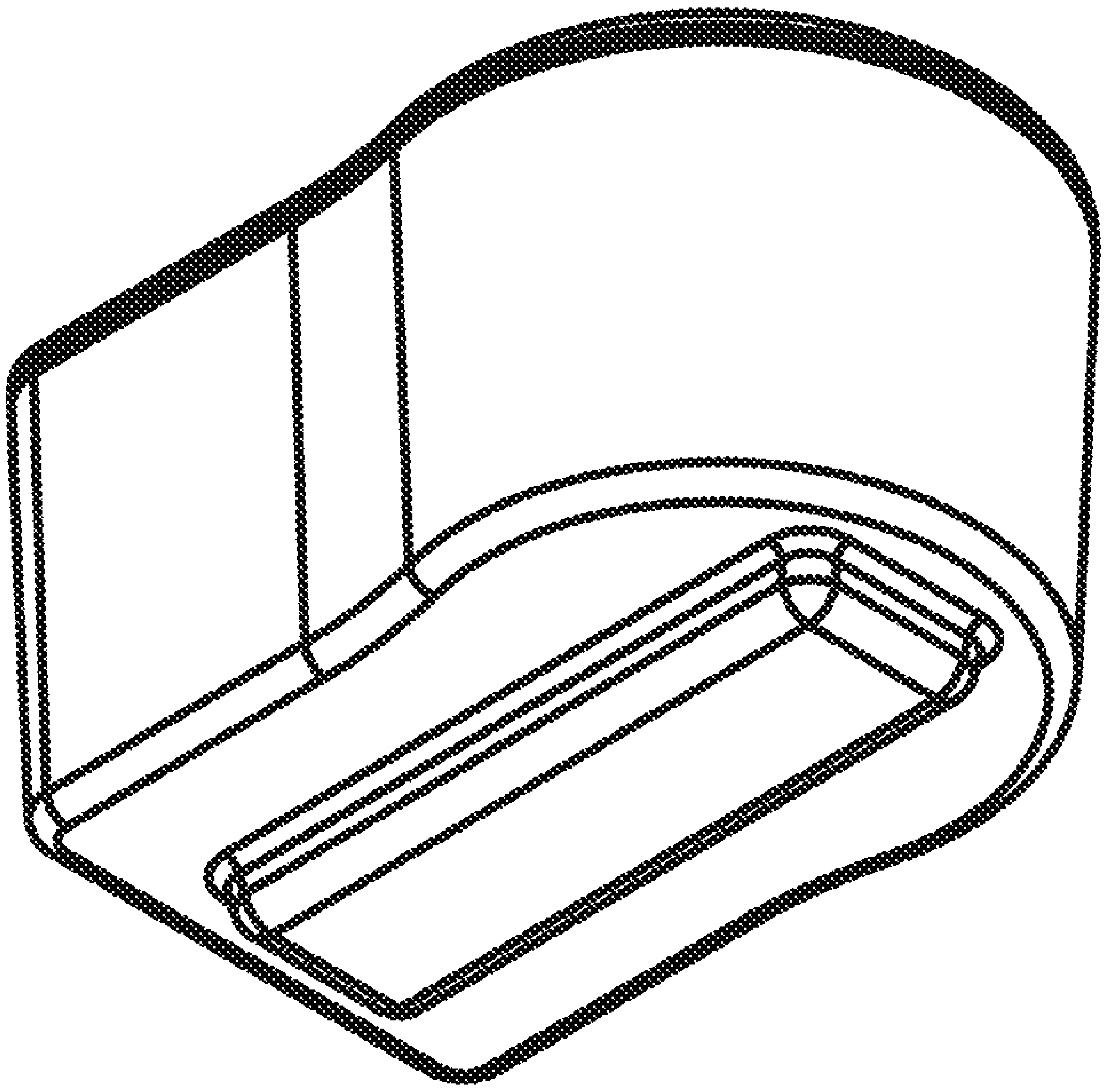


FIG. 7